

L Number	Hits	Search Text	DB	Time stamp
5	274	fbar	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 22:16
6	277	fbar or (film adj bulk adj wave adj resonator)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 22:49
7	114	(fbar or (film adj bulk adj wave adj resonator)) and third	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 22:16
8	37	((fbar or (film adj bulk adj wave adj resonator)) and third) and (bond\$4 or laminat\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 22:47
9	419999	(backside or rear or (lower adj surface) or (back adj surface) or bottom and (bond\$4 or laminat\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 22:48
10	64203	((backside or rear or (lower adj surface) or (back adj surface) or bottom and (bond\$4 or laminat\$4)) and etch\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 22:48
11	35610	(((backside or rear or (lower adj surface) or (back adj surface) or bottom and (bond\$4 or laminat\$4)) and etch\$4) and third	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 22:48
12	102	((((backside or rear or (lower adj surface) or (back adj surface) or bottom and (bond\$4 or laminat\$4)) and etch\$4) and third) and (fbar or (bulk adj wave adj resonator) or (bulk adj acoustic\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 22:49
13	75	((((backside or rear or (lower adj surface) or (back adj surface) or bottom and (bond\$4 or laminat\$4)) and etch\$4) and third) and (fbar or (bulk adj wave adj resonator) or (bulk adj acoustic\$4))) not (((fbar or (film adj bulk adj wave adj resonator)) and third) and (bond\$4 or laminat\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 23:03
14	21	(fbar or (film adj bulk adj wave adj resonator)) and hermetic\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 23:04
15	8	((fbar or (film adj bulk adj wave adj resonator)) and hermetic\$4) and third	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 23:04
16	13	((((backside or rear or (lower adj surface) or (back adj surface) or bottom and (bond\$4 or laminat\$4)) and etch\$4) and third) and (fbar or (bulk adj wave adj resonator) or (bulk adj acoustic\$4))) and hermetic\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 23:06